

## Amendments to the Specification

Please replace the paragraphs designated below with the following amended paragraphs:

Page 5, replace the “Brief Description of the Drawings” with the following paragraph.

“Fig. 1 is a schematic cross sectional view showing a copper clad laminate. Fig. 2 is a photograph taken through an optical microscope, showing a cross section of the copper clad laminate. Fig. 3 is a graph showing a relationship between the reflectance of laser light and the roughness of a material surface. Fig. 4 is a schematic cross sectional view showing an electrodeposited copper foil with carrier. ~~Figs. 5, 6, 7, 8 and 9~~ 5(a)-(h) are schematic explanatory views showing a flow chart for manufacturing a printed wiring board.”

Page 13, replace the paragraph beginning under “Preferred Embodiment of the Present Invention” with the following paragraph.

“In the following, a preferred embodiment of the present invention will be described in more detail to explain a method for manufacturing a printed wiring board, with reference to Figs. 4 [[to 9]] and 5(a)-(h) which are schematic cross sectional views showing a copper clad laminate 1. However, a hole forming test using laser light was conducted by virtue of a low pulse energy of 16 mJ, in order that some advantages and disadvantages of the hole formation process using laser light can be clearly understood. Here, laser irradiation conditions were set such that the frequency was 1000 hz, the mask diameter was 5.0 mm, the pulse width was 60  $\mu$ sec, the pulse energy was 16.0 mJ, the offset was 0.8, and the laser beam diameter was 140  $\mu$ m, thus ensuring the formation of holes each having a diameter of 110  $\mu$ m in the copper clad laminate. Therefore, as a qualification standard, when the holes formed during the laser abrasion had a diameter

distribution in a range from 100  $\mu\text{m}$  to 110  $\mu\text{m}$ , the inventors of the present invention could determine that the result of laser abrasion was acceptable.”

Page 15, replace the paragraph beginning at line 4 with the following paragraph.

“Once the carrier foils 5 were peeled off, the bulk copper layers 6 formed by waved copper foils appeared on the surfaces of the copper clad laminate. At this step, a carbon dioxide laser 7 was used to carry out a hole formation process using laser light. Then, the shape of each via hole 8 was formed in a manner shown in Fig. [[6]] 5(c).”

Page 15, replace the paragraph beginning with “After forming the shape...” with the following paragraph.

“After forming the shape of each via hole 8, a treatment was carried out to form an interlayer electrical connection in a manner shown in Fig. [[7]] 5(d). In fact, the treatment for forming the interlayer electrical connection was carried out by performing an electroless copper plating so as to form a copper layer having a thickness of 1 to 2  $\mu\text{m}$ , followed by an electrolytic copper plating to form a copper layer 9 having a thickness of 10  $\mu\text{m}$ . An electroless copper plating solution actually used was a commonly utilized solution including 0.06 mol/l of copper sulfate pentahydrate, 0.12 mol/l of EDTA 4Na, 0.5 mol/l of HCHO, 10 mg/l of 2,2'-dipyridyl, 250 mg/l of PEG1000, with a pH of 12.5 and a temperature of 70°C. The electroless copper plating was performed in a short time. After the electroless copper plating was completed, an electrolytic plating was performed using a copper sulfate solution containing free sulfuric acid (150 g/l) and copper (65 g/l), under a level plating condition in which the plating temperature

was 45°C and the current density was 15 A/dm<sup>2</sup>, thereby obtaining a copper layer 9 having a thickness of 10  $\mu$ m.”

Page 16, replace the paragraph beginning at line 3 with the following paragraph.

“Subsequently, rinsing and a drying treatment were conducted. An ultraviolet-setting dry film was laminated on to the surface of each bulk copper layer 6 having a copper layer 9 formed thereon, thereby obtaining etching resist layers 10 in a manner shown in Fig. [[7]] 5 (e). Then, patterning films were attached to the etching resist layers 10, followed first by an exposure treatment and then by a development treatment, thereby retaining the etching resist layers 10 only in areas on which predetermined circuits were to be formed, in a manner shown in Fig. [[8]] 5 (f). Afterwards, a cupric chloride etchant was used to carry out an etching treatment, thereby forming circuits in a manner shown in Fig. [[8]] 5 (g). Finally, as shown in Fig. [[9]] 5 (h), a treatment for removing the etching resist layers 10 [[were]] was conducted by using a sodium hydroxide solution, so as to wet remove the hardened etching resist layers 10, thus producing a printed wiring board 11.”